

Abstract

METHOD FOR MANUFACTURING AN ELECTRONIC DEVICE COMPRISING A
NON-REMOVABLE MODULE, AND RESULTING DEVICE

The invention relates to a method for manufacturing an electronic device (13a, 13b), including a module (1, 15) attached in a recess of a carrier body, said module including a backing film (2) having a metal coating (3) on an upper surface side and on a lower surface side, an integrated-circuit chip (6) connected to the metal coating using electric connection wires (7, 8), the integrated-circuit chip being coated with a coating and mechanically protective material (9). The method is characterized in that it includes an anchoring step according to which a second anchoring material (11) is provided for bonding a portion (7p, 8p, 17p, 18p) of at least one of said electric wires and for anchoring said wire portion to the carrier body.

Figure 8